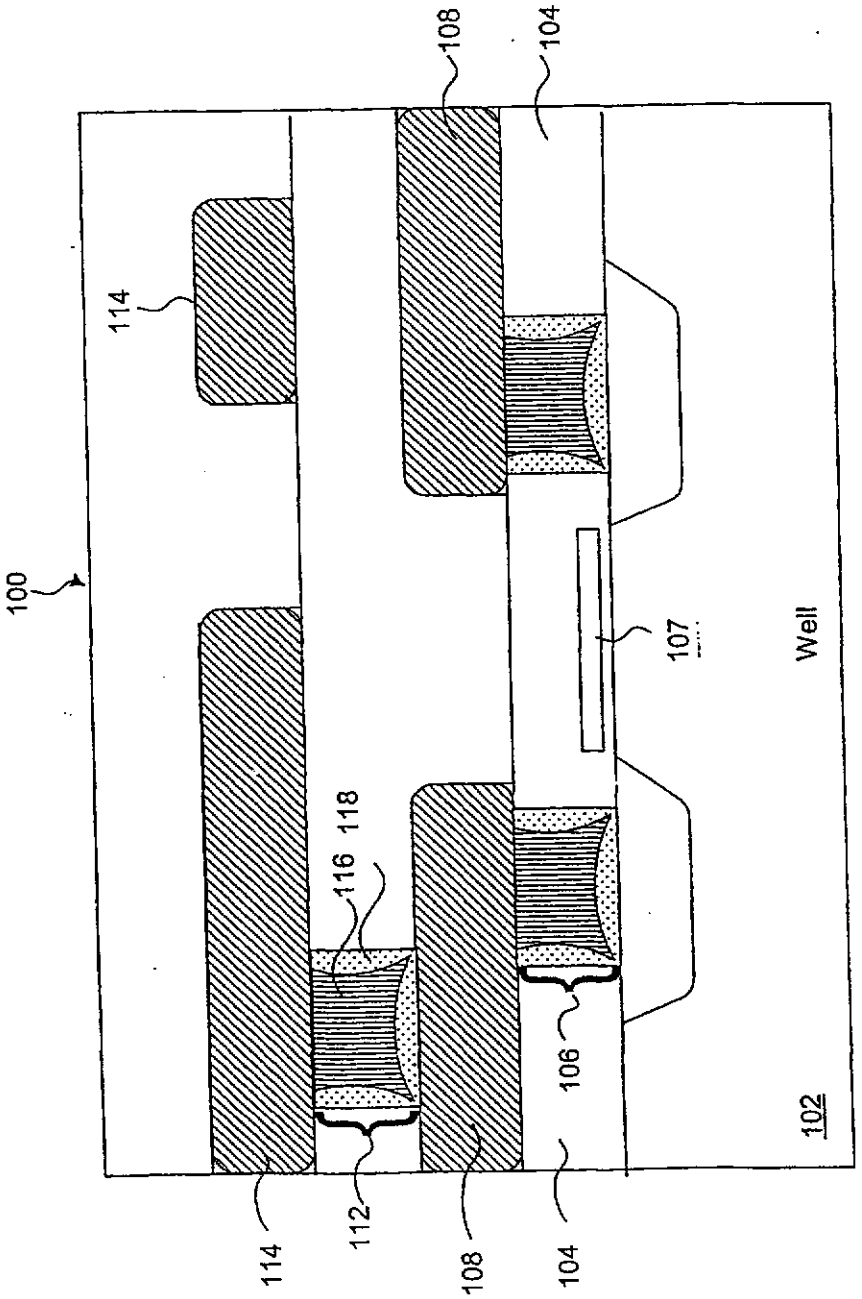


FIG. 1(Prior Art)

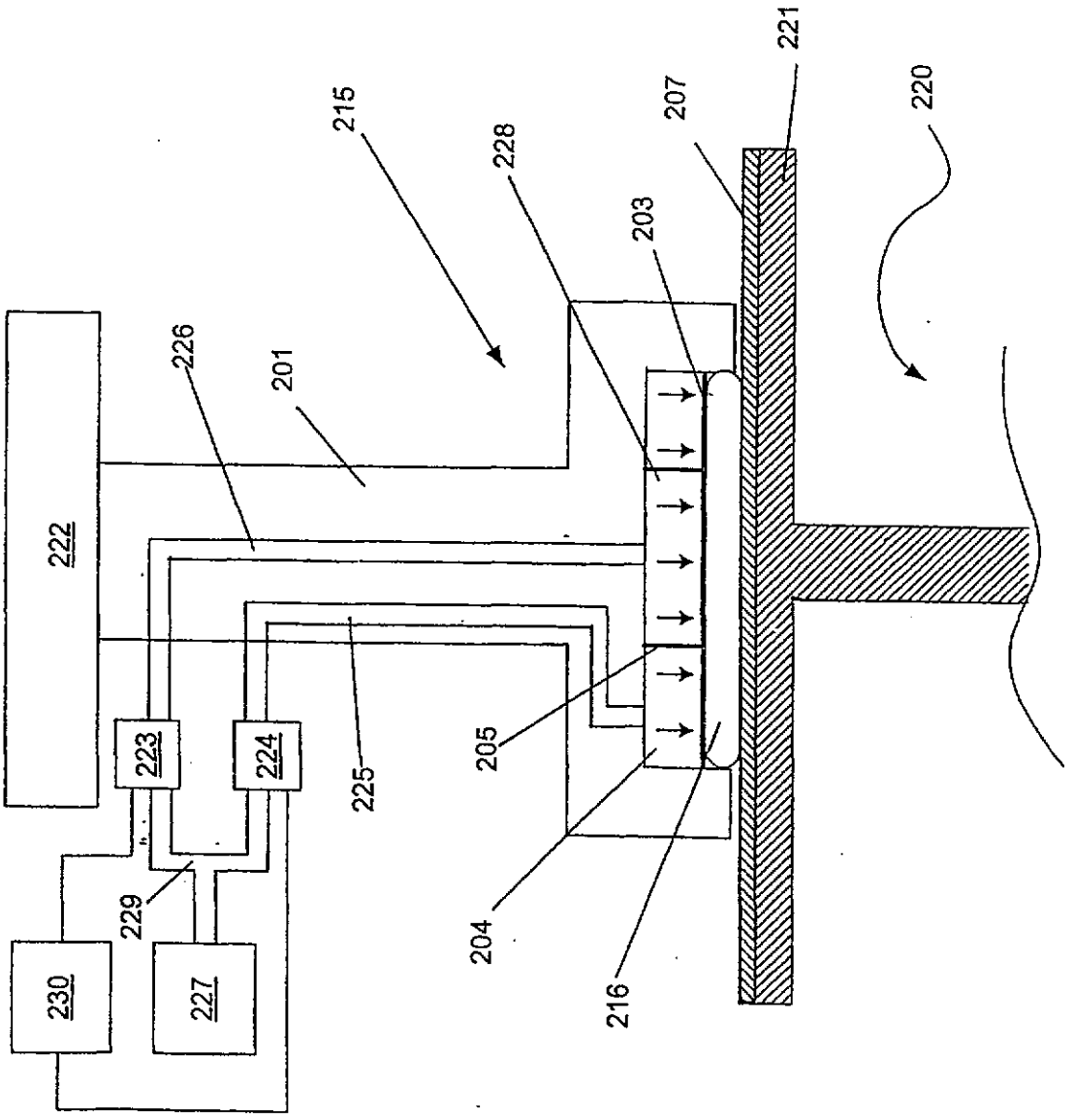

221
220
215
228
207
203
226
201
222
223
224
225
205
229
204
216
230
227

FIG. 2

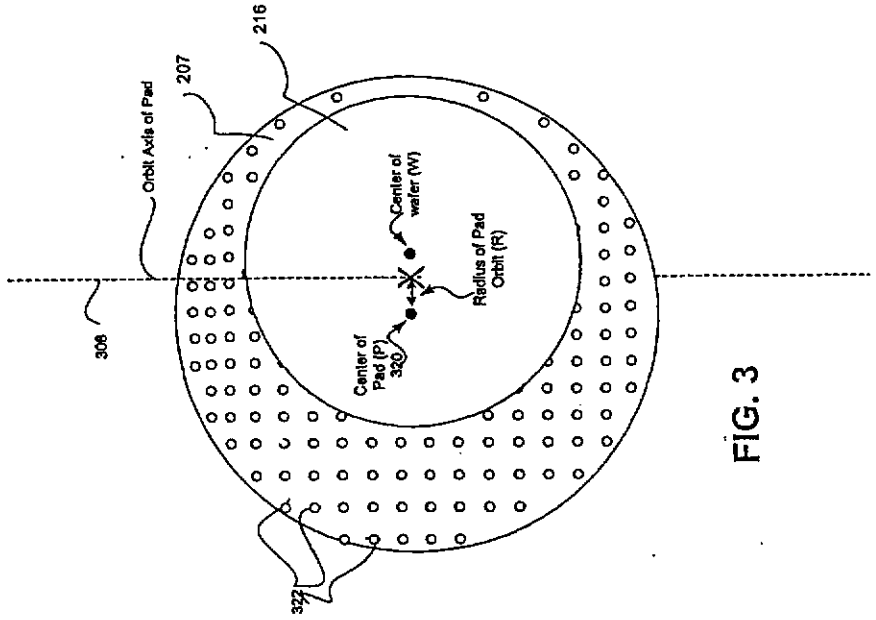

216
207
Orbit Axis of Pad
Center of wafer (W)
Radius of Pad Orbit (R)
Center of Pad (P) 320
308
327

FIG. 3

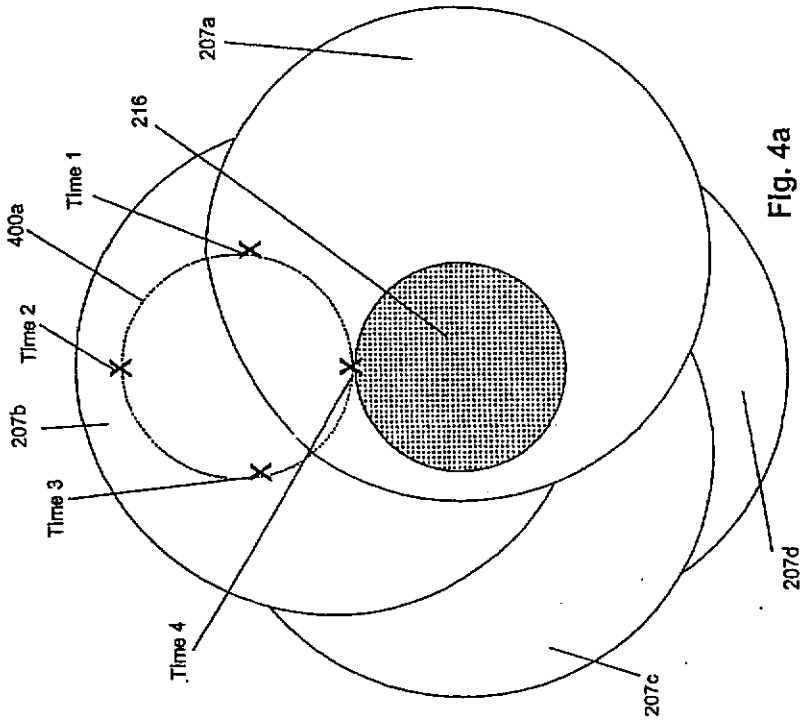

207a
216
Time 1
400a
Time 2
207b
Time 3
Time 4
207d
207c

Fig. 4a

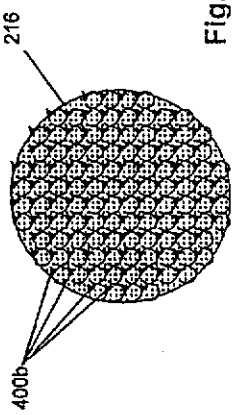

216
400b

Fig. 4b

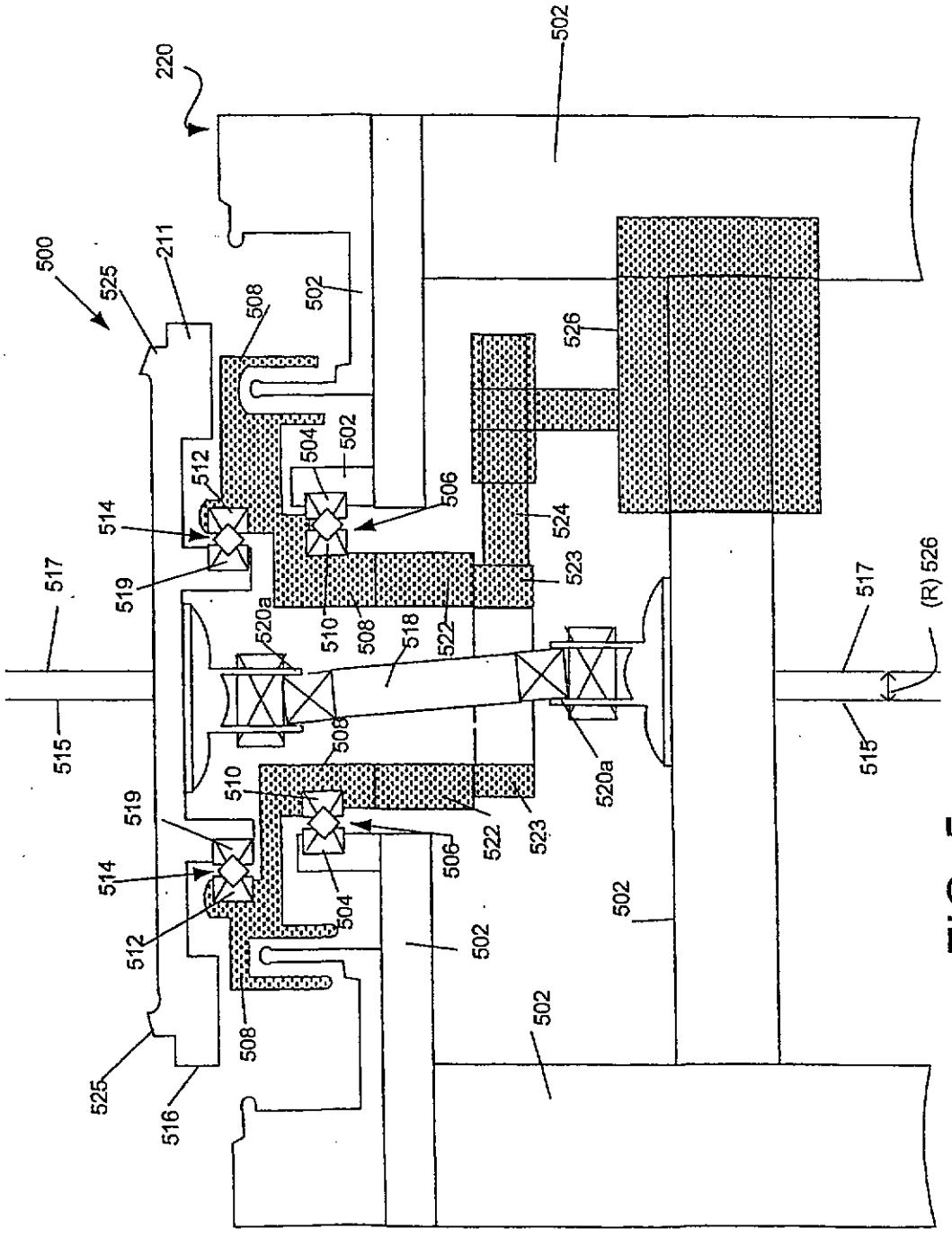

220
502
500
525
211
508
502
526
504
502
512
506
514
524
523
517
519
520a
510
508
518
522
(R) 526
515
520a
510
519
522
523
506
514
504
502
512
502
508
502
525
516

FIG. 5

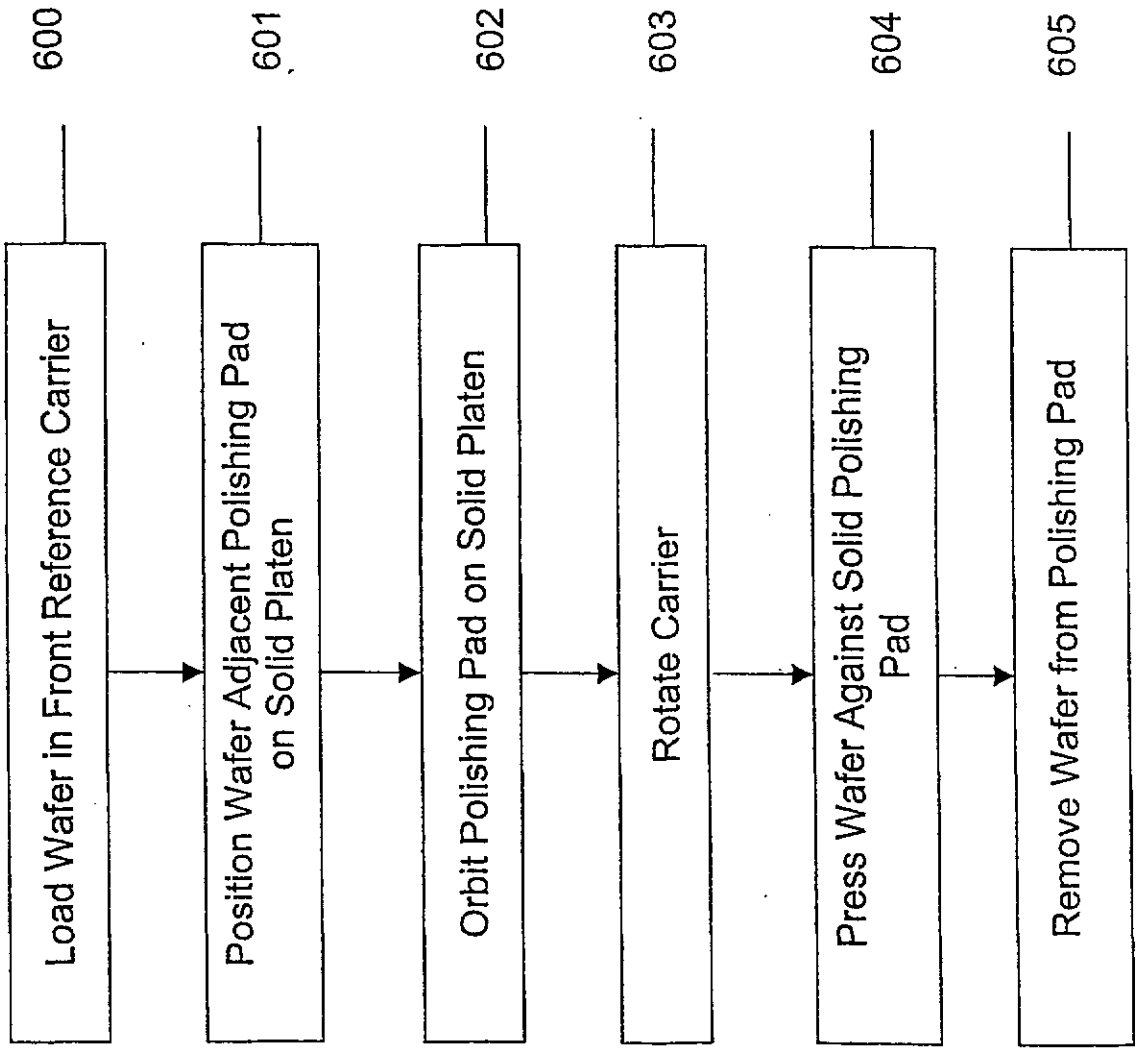

600
Load Wafer in Front Reference Carrier
601
Position Wafer Adjacent Polishing Pad on Solid Platen
602
Orbit Polishing Pad on Solid Platen
603
Rotate Carrier
604
Press Wafer Against Solid Polishing Pad
605
Remove Wafer from Polishing Pad

FIG. 6